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## **Question Paper Code: 46404**

## B.E. / B.Tech. DEGREE EXAMINATION, DEC 2020

Sixth Semester

## **Electronics and Communication Engineering**

## 14UEC604-VLSI DESIGN

		(Regu	lation 2014)				
Dura	tion: 1.15 hrs			Maximum: 30 Marks			
	I	PART A -	$(6 \times 1 = 6 \text{ Ma})$	arks)			
(Answer any six of the following questions)							
1. VL	SI technology uses	to f	form integrated	d circuit.			
	(a) Transistors (b) Sv	witches (	(c) Diodes	(d) Buffers			
2. The	2. The difficulty in achieving high doping concentration leads to						
	(a) Error in concentration		(b)	Error in variation			
	(c) Error in doping		(d) ]	Distribution			
(	(a) The capacitor to be character (b) The voltage through who (c) Available current (d) All of the above	rged		ay of the logic circuit depends on e charged			
4. In C	CMOS circuits, which type	of power	dissipation oc	curs due to switching of transient			

(b) Dynamic dissipation

(d) None of the above

current & discharging of load capacitance?

(a) Static dissipation

(c) Both a and b

5.	(a) The trigger pulse is given to che (b) Any pulse given to go into prev (c) They don't get any pulse more (d) None of the Mentioned	nange the state vious state	
6. 7	The sequential circuit is also called		
	(a) Flip-flop (b) Latch	(c) Strobe	(d) None of the Mentioned
7.	Boundary scan test is used to test		
	(a) Pins (b) Multiplie	ers (c) Boards	(d) wires
8.	CMOS domino logic occupies		
	(a) Smaller area	(b) Larger are	ea
9.	(c) Both of the mentioned  Test Benches procedure is	(d) None of	the mentioned
	(a) Smaller design	(b) Larger de	sign
10.	(c) Complicated Blocking & Non blocking assignment	(d) None of the	ne mentioned
	<ul><li>(a) =statement &amp; ≤ statement</li><li>(c) Statement</li></ul>	(b) ≤ statemed $(d)$ ≥ statemed	ent & =statement
	PART – B	3 (3 x 8= 24 Marks)	
	(Answer any three	of the following qu	estions)
11.	Explain layout design rules in detail	il.	(8)
12.	Explain in detail about delay estimate	ation, logical effort	and transistor sizing with
	example.		(8)
13.	Explain in detail: (i) Conventiona	al CMOS Latch (ii)	Conventional CMOS Flip flop (8)
14.	What are the various testing me circuit?	ethods to be consid	ered while designing a VLS
15.	Explain the concept involved in description for Decoder and parity	_	el modeling and also give the